



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTN9970LV	Issued	09. February 2022
MA#	MA005547818		
Package	PG-HSOF-7-1	Weight*	346.11 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.628	0.18	0.18	1814	1814
chip_2	inorganic material	silicon	7440-21-3	0.388	0.11	0.11	1120	1120
chip_3	inorganic material	silicon	7440-21-3	0.768	0.22	0.22	2220	2220
leadframe	inorganic material	phosphorus	7723-14-0	0.055	0.02		158	
	non noble metal	iron	7439-89-6	0.182	0.05		525	
	non noble metal	copper	7440-50-8	181.611	52.47	52.54	524713	525396
wire	non noble metal	copper	7440-50-8	0.157	0.05	0.05	454	454
encapsulation	inorganic material	zinc oxide	1314-13-2	1.528	0.44		4414	
	miscellaneous	miscellaneous	-	6.112	1.77		17658	
	plastics	epoxy resin	-	22.918	6.62		66216	
	inorganic material	silicon dioxide	60676-86-0	122.232	35.32	44.15	353153	441441
lead finish	non noble metal	tin	7440-31-5	2.025	0.58	0.58	5850	5850
plating	noble metal	silver	7440-22-4	0.271	0.08	0.08	784	784
solder	non noble metal	tin	7440-31-5	0.033	0.01		97	
	noble metal	silver	7440-22-4	0.042	0.01		121	
	non noble metal	lead	7439-92-1	1.595	0.46	0.48	4609	4827
glue	plastics	Polyimide	26023-21-2	0.126	0.04	0.04	364	364
heat sink clip	inorganic material	phosphorus	7723-14-0	0.002			5	
	non noble metal	iron	7439-89-6	0.005			16	
	non noble metal	copper	7440-50-8	5.437	1.57	1.57	15709	15730
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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